Dylan Cheung

SOFTWARE ENGINEER

21-27 Temple PI Boston, MA 02111

dylancheung123@gmail.com dylancheung123.github.io

SKILLS

Programming Languages

TypeScript JavaScript Python Java C++ C

Frameworks

HTML React Node CSS

Hardware Controllers

Raspberry Pi Arduino

Other Programs

Blender Unity

HONORS AND AWARDS

Rensselaer Leadership Award Dean's List

ACTIVITIES

JDRF - Ride to Cure T1D RPISEC/INTROSEC RPI Club Lacrosse

WORK EXPERIENCE

HiMarley

Software Engineer

January 2019 - Present Boston, MA

- Gained exposure to working in an Agile team to develop a Node.js-based Al application to facilitate communication for insurance claims via multiple communication channels.
- Converted a single availability zone application into an auto-scaling cross-region system utilizing AWS services.

Surefluence Inc.

Summer 2018

Junior Software Engineer

Troy, NY

- Collaborated on the development of Surefluence's distributed crawler platform during their MVP product stage.
- Led development using the SCRUM methodology for a scalable data-ingest service/pipeline in Node.js over Redis with highly optimized and normalized schemas in PostgreSQL.
- Produced highly-transparent analytic insights over web-sockets with a strong emphasis on the asynchronous event loop and a distributed architecture.

Rensselaer Polytechnic Institute

Fall 2017 Troy, NY

Undergraduate Researcher

- Instrumental in designing/producing a computer-vision subsystem for autonomous Micro Air Vehicle (MAV) operation.

EDUCATION

Rensselaer Polytechnic Institute

B.S. - Computer Science (Systems & Software)

2015 - 2019

3.25 GPA

Relevant Coursework

- Security Engineering
- Database Systems
- Principles of Software
- Software Design & Doc
- Operating Systems
- Computer Organization
- Programming Languages
- Data Structures

PROJECTS

Rensselaer Center for Open Source

Fullstack Developer

Fall 2018 Troy, NY

- Led efforts to migrate backend architecture to modern TypeScript with ES7 paradigms backed by high coverage unit testing.
- Streamlined frontend development through the use of intelligent lowly coupled and highly cohesive component decorators.